

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A method of manufacturing ~~a thin film element chips~~, comprising:

forming element chips including at least one of a plurality of ~~functional elements~~  
thin film transistor circuits on a first substrate through a peel layer;

adhering a second flexible substrate onto the element chips through an adhesive layer;

transferring the element chips onto the second flexible substrate peeled from the first substrate, the element chips being rectangular; and

arranging short sides of the element chips along a curving direction of the second substrate.

2-5. (Canceled)

6. (Currently Amended) An electronic apparatus, comprising:

~~the electro-optical device according to Claim 5.~~

~~element chips including at least one of a plurality of the electronic apparatus;~~  
and

~~the electronic apparatus including thin film transistor circuits manufactured by~~  
the method of manufacturing the element chips according to claim 1.